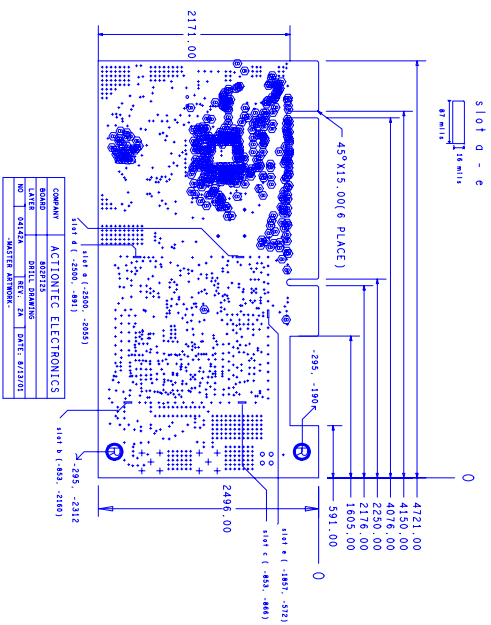


DRILL CHART				
All Units are in mils				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
●	8.0	3.0	PLATED	370
•	12.0	3.0	PLATED	1121
+	16x87	3.0	PLATED	4
—	87x16	3.0	PLATED	1
•	20.0	3.0	PLATED	16
•	30.0	3.0	PLATED	2
•	35.0	3.0	PLATED	4
•	35.0	3.0	PLATED	4
+	70.0	3.0	PLATED	10
R	125.0	3.0	NOT PLATED	2



- NOTES: 1. USE 1/2 OZ. COPPER + PLATING ON EXTERNAL LAYERS.
2. OVERALL THICKNESS EXCLUDES PROTECTIVE COATING.
3. FROM COPPER TO COPPER.
4. ALL EXPOSED COPPER SURFACES SHALL BE IMMERSION GOLD.
5. 1 MIL COPPER MAINTAINED IN ALL PLATED THROUGH HOLES.
6. ON LAYERS 1,4 ENSURE COPPER WEIGHT AND PLATING ARE WITHIN 2.1-10%
7. ON LAYER 2, 3 ENSURE THAT COPPER WEIGHT IS 1 OZ ie 1.4mi +/-0%
8. ENSURE DIELECTRIC HEIGHT FROM LAYERS 1 TO 2 AND LAYERS 3 TO 4 IS 10MILS +/-10%
9. ENSURE DIELECTRIC HEIGHT FROM LAYERS 2 TO 3 IS 36MILS +/-1 MIL MAX
10. ENSURE THAT COPPER TRACES AND SPACING ARE HELD TO +1 MIL/-0 MIL
11.(APPLY TO ARRAY ONLY)

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TDR COUPON REQUIRED. COPLANAR CONSTRUCTION: MAIN
CONDUCTOR TRACE WIDTH IS 8 MILS ON LAYER1.
LAYER1 HAS GROUND FILL WITH 6.5 MIL SPACING ON BOTH
SIDES OF TRACE. LAYER2 HAS GROUND FILL.

12.(APPLY TO PANEL ONLY)
TDR COUPON REQUIRED. MICROSTRIP CONSTRUCTION: MAIN
CONDUCTOR TRACE WIDTH IS 16MILS ON LAYER1. LAYER1 HAS
NO GROUND FILL. LAYER2 HAS GROUND FILL.

13.(APPLY TO PANEL ONLY)
TDR COUPON REQUIRED. STRIPLINE CONSTRUCTION: MAIN
CONDUCTOR TRACE WIDTH IS 5 MILS ON LAYER 2. LAYER 2
HAS GROUND FILL WITH 10MILS SPACING ON BOTH SIDES OF
TRACE. LAYER1 AND LAYER 3 WILL HAVE GROUND FILL.
14. CORE MATERIAL SHALL BE COPPER CLAD FR4. (Er=4.2)
15. MINIMUM CONDUCTOR WIDTH SHALL BE 5 MILS.
MINIMUM SPACING SHALL BE 5 MILS, EXCEPT IN BGA AREA
WHERE MINIMUM SPACING SHALL BE 4 MILS.

16. USE BLUE SOLDERMASK (COLOR SAMPLE AVAILABLE ON REQUEST)

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